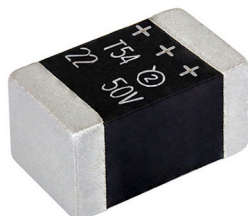


# vPolyTan™ Polymer Surface-Mount Chip Capacitors, Low ESR, Leadframeless Molded Type, DLA Approved



## LINKS TO ADDITIONAL RESOURCES



## FEATURES

- Ultra low ESR
- Tin / lead (SnPb) termination
- High reliability processing including:
  - 100 % surge current tested
  - Thermal shock
  - Statistical DC leakage screening at elevated temperature and voltage, covered by U.S. patent and worldwide patents pending.
- PATENT(S): [www.vishay.com/patents/](http://www.vishay.com/patents/)
- High ripple current capability
- Stable capacitance over operating temperature, voltage, and frequency range
- No wear out effect
- Moisture sensitivity level 3

## PERFORMANCE CHARACTERISTICS

**Operating Temperature:** -55 °C to +125 °C  
(above 105 °C, additional voltage derating is required)

### Capacitance range:

15 µF to 470 µF (discrete capacitors)  
30 µF to 2800 µF (stacked capacitors)

**Capacitance Tolerance:** ± 20 %

**Voltage Rating:** 16 V<sub>DC</sub> to 75 V<sub>DC</sub>

### Note

- Recommended voltage derating guidelines per DLA LAND AND MARITIME drawing 20021

ORDERING INFORMATION			
20021	-001 <sup>(1)</sup>	A	/HR <sup>(2)</sup>
DRAWING NUMBER	DASH NUMBER	SURGE CURRENT OPTION	PACKAGING
		A = 10 cycles at +25 °C B = 10 cycles at -55 °C / +85 °C S = 6 cycles at +25 °C (all surge current tests are performed after voltage aging)	Discrete components: blank = full 7" reel /HR = half 7" reel Stack components: blank = formed tray

### Notes

- (1) Dash number -001 for DISCRETE COMPONENT; -201 for STACK COMPONENT  
 (2) Discrete components are shipped in tape and reel packaging only. Stack components are shipped in formed tray packaging only

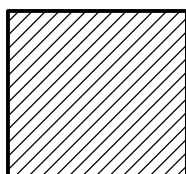
DLA LAND AND MARITIME COLUMBUS, OHIO	Drawing no. 20021
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PATENT(S): [www.vishay.com/patents](http://www.vishay.com/patents/)

This Vishay product is protected by one or more United States and international patents.

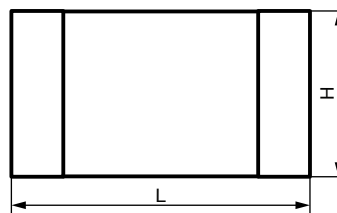
**EE CASE: DISCRETE COMPONENT DIMENSIONS** in inches [millimeters]

Cathode (-) end view

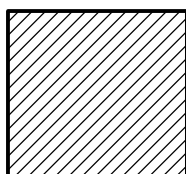


Solderable surface

Side view

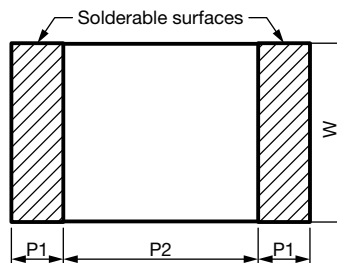


Anode (+) end view



Solderable surface

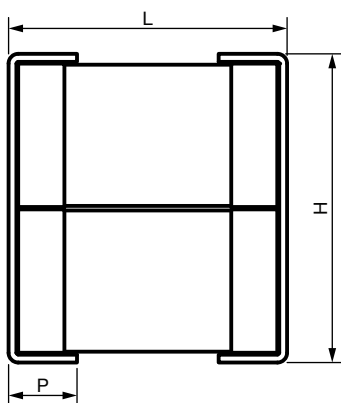
Bottom view



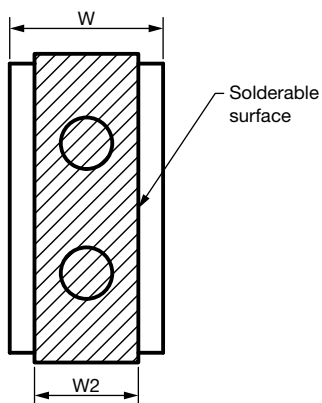
CASE CODE	EIA SIZE	H (MAX.)	L	W	P1	P2 (REF.)
EE	7343-43	0.169 [4.3]	0.287 ± 0.012 [7.3 ± 0.3]	0.169 ± 0.012 [4.3 ± 0.3]	0.051 ± 0.012 [1.3 ± 0.3]	0.191 [4.85]

**E2 CASE: 2 COMPONENT STACK DIMENSIONS** in inches [millimeters]

Side view

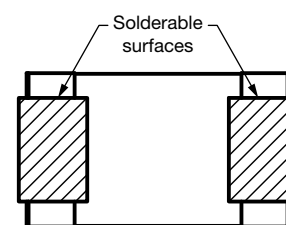


Anode (+) / cathode (-) end view



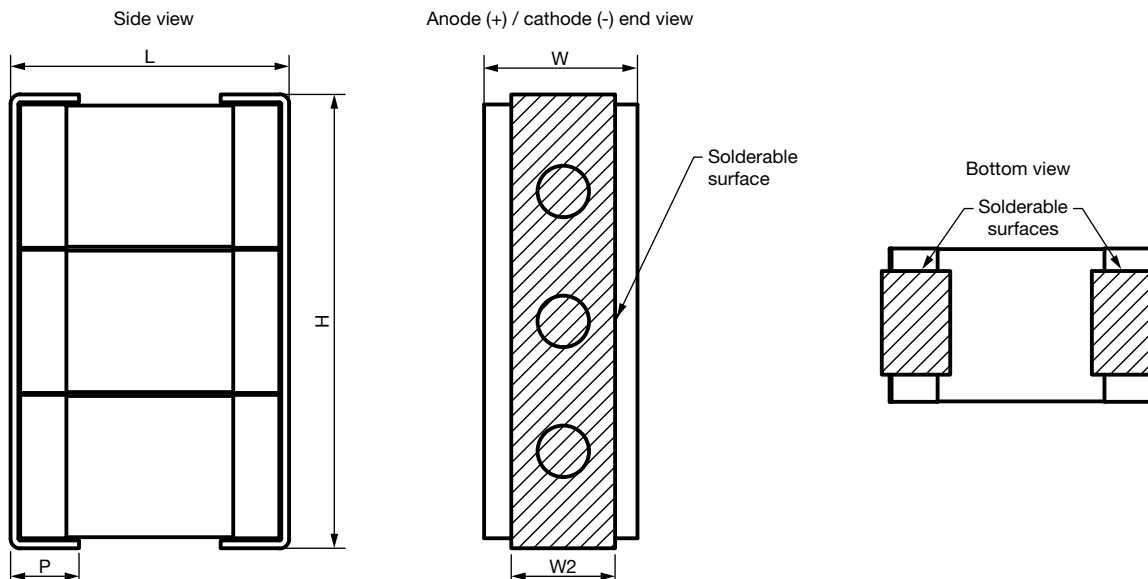
Solderable surface

Bottom view

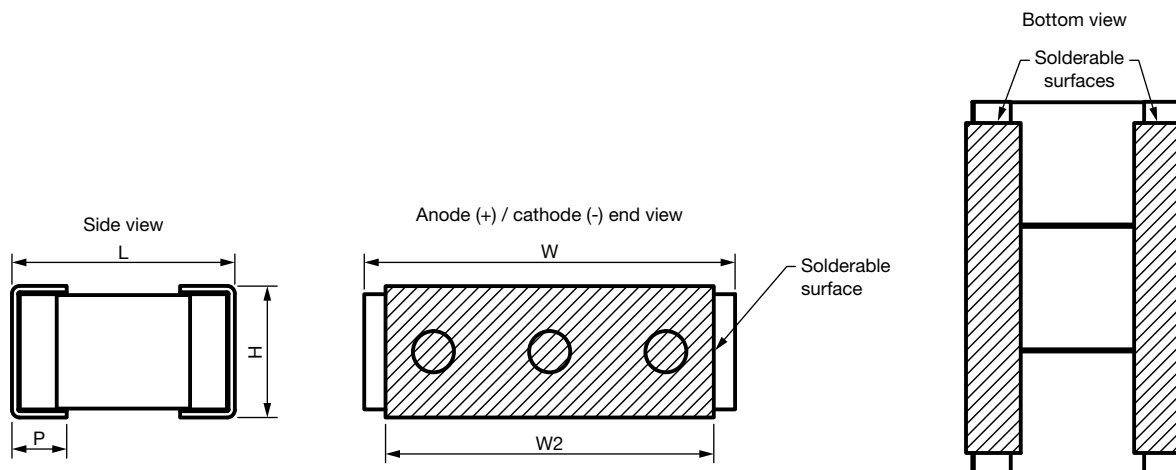


Solderable surfaces

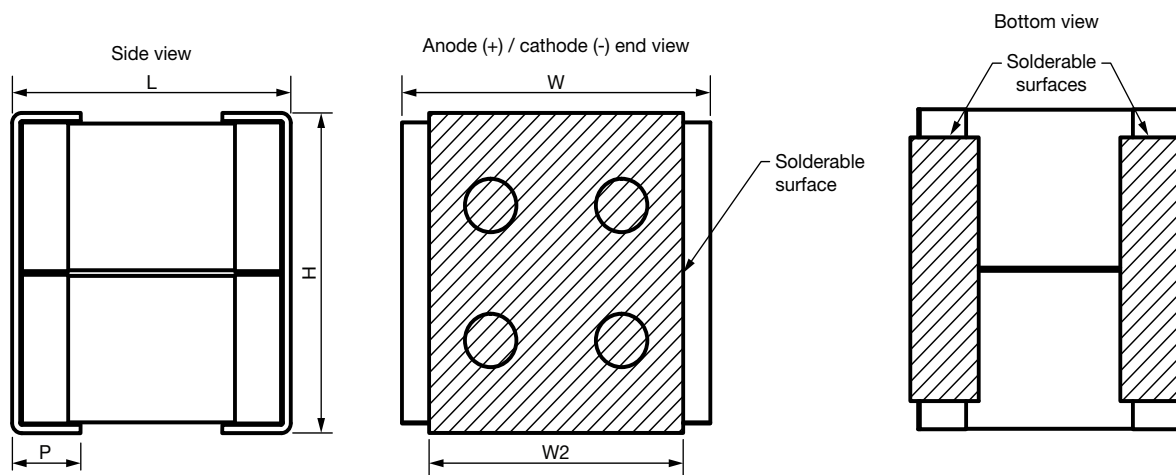
CASE CODE	L	W	H	W2	P
E2	0.315 ± 0.015 [8.0 ± 0.38]	0.174 ± 0.008 [4.4 ± 0.2]	0.352 ± 0.015 [8.9 ± 0.38]	0.120 ± 0.008 [3.0 ± 0.2]	0.075 ± 0.015 [1.9 ± 0.38]

**E3 CASE: 3 COMPONENT STACK DIMENSIONS** in inches [millimeters]


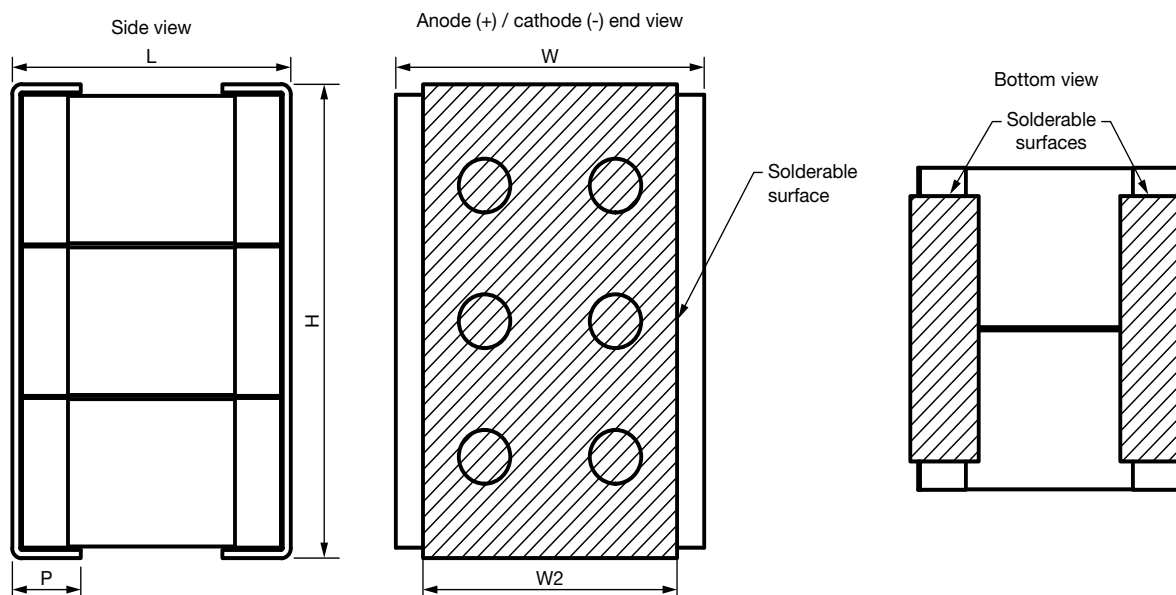
CASE CODE	L	W	H	W2	P
E3	$0.315 \pm 0.015$ [8.0 ± 0.38]	$0.174 \pm 0.008$ [4.4 ± 0.2]	$0.525 \pm 0.015$ [13.3 ± 0.38]	$0.120 \pm 0.008$ [3.0 ± 0.2]	$0.075 \pm 0.015$ [1.9 ± 0.38]

**3E CASE: 3 COMPONENT STACK DIMENSIONS** in inches [millimeters]


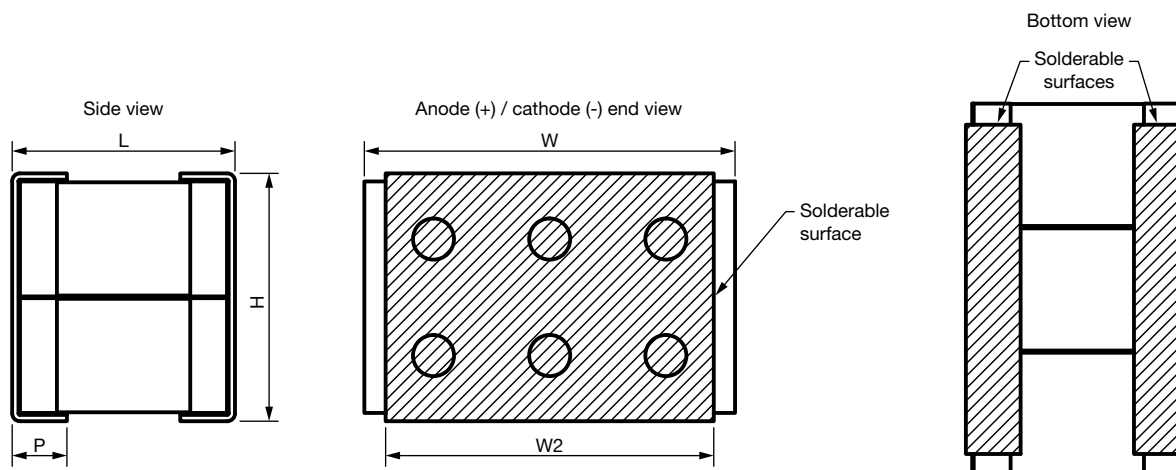
CASE CODE	L	W	H	W2	P
3E	$0.315 \pm 0.015$ [8.0 ± 0.38]	$0.535 \pm 0.008$ [13.6 ± 0.2]	$0.189 \pm 0.008$ [4.8 ± 0.2]	$0.472 \pm 0.008$ [12.0 ± 0.2]	$0.075 \pm 0.015$ [1.9 ± 0.38]

**E4 CASE: 4 COMPONENT STACK DIMENSIONS** in inches [millimeters]


CASE CODE	L	W	H	W2	P
E4	$0.315 \pm 0.015$ [8.0 ± 0.38]	$0.350 \pm 0.008$ [8.9 ± 0.2]	$0.352 \pm 0.015$ [8.9 ± 0.38]	$0.292 \pm 0.008$ [7.4 ± 0.2]	$0.075 \pm 0.015$ [1.9 ± 0.38]

**E6 CASE: 6 COMPONENT STACK DIMENSIONS** in inches [millimeters]


CASE CODE	L	W	H	W2	P
E6	$0.315 \pm 0.015$ [8.0 ± 0.38]	$0.350 \pm 0.008$ [8.9 ± 0.2]	$0.525 \pm 0.015$ [13.3 ± 0.38]	$0.292 \pm 0.008$ [7.4 ± 0.2]	$0.075 \pm 0.015$ [1.9 ± 0.38]

**6E CASE: 6 COMPONENT STACK DIMENSIONS** in inches [millimeters]


CASE CODE	L	W	H	W2	P
6E	0.315 ± 0.015 [8.0 ± 0.38]	0.535 ± 0.008 [13.6 ± 0.2]	0.352 ± 0.015 [8.9 ± 0.38]	0.472 ± 0.008 [12.0 ± 0.2]	0.075 ± 0.015 [1.9 ± 0.38]

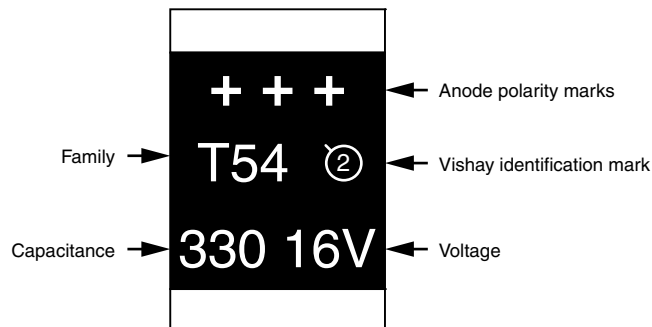
**CASE EE: RATINGS AND CASE CODES (ESR mΩ)**

μF	16 V	30 V	35 V	50 V	63 V	75 V
15					EE (100)	
22				EE (100)	EE (100)	EE (100)
47			EE (70)	EE (100, 70)		
150		EE (150, 75)				
220	EE (25)					
330	EE (25)					
470	EE (25)					

**CASES Ex / xE <sup>(1)</sup>: RATINGS AND CASE CODES (ESR mΩ)**

μF	16 V	30 V	35 V	50 V	63 V	75 V
30					E2 (50)	
45				E2 (50)	E2 (50); E3 / 3E (35)	E2 (50)
60					E4 (25)	
66				E3 / 3E (35)	E3 / 3E (35)	E3 / 3E (35)
90				E4 (25)	E4 (25); E6 / E6 (17)	E4 (25)
95			E2 (35, 28)	E2 (50)		
130				E6 / 6E (17)	6E / E6 (17)	6E / E6 (17)
140			E3 / 3E (25, 18)	E3 / 3E (35)		
190			E4 (18, 14)	E4 (25)		
280			E6 / 6E (12, 10)	E6 / 6E (17)		
300		E2 (75, 38)				
450	E2 (13)	E3 / 3E (50, 25)				
600		E4 (38, 20)				
660	E2 (13); E3 / 3E (9)					
900	E4 (7)	E6 / 6E (25, 13)				
940	E2 (13, 10)					
990	E3 / 3E (9)					
1300	E4 (7); E6 / 6E (5)					
1400	E3 / 3E (9, 7)					
1900	E4 (7, 5)					
2000	E6 / 6E (5)					
2800	E6 / 6E (5)					

**Note**
<sup>(1)</sup> Contact marketing for availability of stacked capacitors

**MARKING**

**CASE EE: DISCRETE COMPONENT STANDARD RATINGS**

CAPACITANCE ( $\mu$ F)	CASE CODE	PART NUMBER	MAX. DCL AT +25 °C ( $\mu$ A)	MAX. DF AT +25 °C 120 Hz (%)	MAX. ESR AT + 25 °C 100 kHz (m $\Omega$ )	MAX. RIPPLE, 100 kHz $I_{RMS}$ (A)
<b>16 V<sub>DC</sub> AT +105 °C, 10 V<sub>DC</sub> AT +125 °C</b>						
220	EE	20021-001(1)(2)	352	10	25	4.195
330	EE	20021-002(1)(2)	528	10	25	4.195
470	EE	20021-003(1)(2)	752	10	25	4.195
<b>30 V<sub>DC</sub> AT +105 °C, 20 V<sub>DC</sub> AT +125 °C</b>						
150	EE	20021-004(1)(2)	450	10	150	1.713
150	EE	20021-005(1)(2)	450	10	75	2.422
<b>35 V<sub>DC</sub> AT +105 °C, 25 V<sub>DC</sub> AT +125 °C</b>						
47	EE	20021-006(1)(2)	165	10	70	2.507
<b>50 V<sub>DC</sub> AT +105 °C, 33 V<sub>DC</sub> AT +125 °C</b>						
22	EE	20021-007(1)(2)	110	10	100	2.098
47	EE	20021-010(1)(2)	235	10	100	2.098
47	EE	20021-011(1)(2)	235	10	70	2.507
<b>63 V<sub>DC</sub> AT +105 °C, 43 V<sub>DC</sub> AT +125 °C</b>						
15	EE	20021-008(1)(2)	95	10	100	2.098
22	EE	20021-009(1)(2)	139	10	100	2.098
<b>75 V<sub>DC</sub> AT +105 °C, 50 V<sub>DC</sub> AT +125 °C</b>						
22	EE	20021-012(1)(2)	165	12	100	2.098

**Notes**

- Part number definitions:
  - (1) Surge current: blank, A, B, S
  - (2) Packaging: blank, /HR

**CASE Ex / xE: STACK COMPONENT STANDARD RATINGS**

CAPACITANCE ( $\mu$ F)	CASE CODE	PART NUMBER	MAX. DCL AT +25 °C ( $\mu$ A)	MAX. DF AT +25 °C 120 Hz (%)	MAX. ESR AT + 25 °C 100 kHz (m $\Omega$ )	MAX. RIPPLE, 100 kHz I <sub>RMS</sub> (A)
<b>16 V<sub>DC</sub> AT +105 °C, 10 V<sub>DC</sub> AT +125 °C</b>						
450	E2	20021-201(1)(2)	704	10	13	6.794
660	E2	20021-202(1)(2)	1056	10	13	6.794
660	E3	20021-203(1)(2)	1056	10	9	8.165
660	3E	20021-204(1)(2)	1056	10	9	8.165
900	E4	20021-205(1)(2)	1408	10	7	9.258
940	E2	20021-206(1)(2)	1504	10	13	6.794
940	E2	20021-207(1)(2)	1504	10	10	7.746
990	E3	20021-208(1)(2)	1584	10	9	8.165
990	3E	20021-209(1)(2)	1584	10	9	8.165
1300	E4	20021-210(1)(2)	2112	10	7	9.258
1300	E6	20021-211(1)(2)	2112	10	5	10.954
1300	6E	20021-212(1)(2)	2112	10	5	10.954
1400	E3	20021-213(1)(2)	2256	10	9	8.165
1400	E3	20021-214(1)(2)	2256	10	7	9.258
1400	3E	20021-215(1)(2)	2256	10	9	8.165
1400	3E	20021-216(1)(2)	2256	10	7	9.258
1900	E4	20021-217(1)(2)	3008	10	7	9.258
1900	E4	20021-218(1)(2)	3008	10	5	10.954
2000	E6	20021-219(1)(2)	3168	10	5	10.954
2000	6E	20021-220(1)(2)	3168	10	5	10.954
2800	E6	20021-221(1)(2)	4512	10	5	10.954
2800	6E	20021-222(1)(2)	4512	10	5	10.954
<b>30 V<sub>DC</sub> AT +105 °C, 20 V<sub>DC</sub> AT +125 °C</b>						
300	E2	20021-223(1)(2)	900	10	75	2.828
300	E2	20021-224(1)(2)	900	10	38	3.974
450	E3	20021-225(1)(2)	1350	10	50	3.464
450	E3	20021-226(1)(2)	1350	10	25	4.899
450	3E	20021-227(1)(2)	1350	10	50	3.464
450	3E	20021-228(1)(2)	1350	10	25	4.899
600	E4	20021-229(1)(2)	1800	10	38	3.974
600	E4	20021-230(1)(2)	1800	10	20	5.477
900	E6	20021-231(1)(2)	2700	10	25	4.899
900	E6	20021-232(1)(2)	2700	10	13	6.794
900	6E	20021-233(1)(2)	2700	10	25	4.899
900	6E	20021-234(1)(2)	2700	10	13	6.794
<b>35 V<sub>DC</sub> AT +105 °C, 25 V<sub>DC</sub> AT +125 °C</b>						
95	E2	20021-235(1)(2)	330	10	35	4.140
95	E2	20021-236(1)(2)	330	10	28	4.629
140	E3	20021-237(1)(2)	495	10	25	4.899
140	E3	20021-238(1)(2)	495	10	18	5.774
140	3E	20021-239(1)(2)	495	10	25	4.899
140	3E	20021-240(1)(2)	495	10	18	5.774
190	E4	20021-241(1)(2)	660	10	18	5.774
190	E4	20021-242(1)(2)	660	10	14	6.547
280	E6	20021-243(1)(2)	990	10	12	7.071
280	E6	20021-244(1)(2)	990	10	10	7.746
280	6E	20021-245(1)(2)	990	10	12	7.071
280	6E	20021-246(1)(2)	990	10	10	7.746

**Notes**

- Part number definitions:
  - (1) Surge current: blank, A, B, S
  - (2) Packaging: blank, /HR

**CASE Ex / xE: STACK COMPONENT STANDARD RATINGS**

CAPACITANCE ( $\mu$ F)	CASE CODE	PART NUMBER	MAX. DCL AT +25 °C ( $\mu$ A)	MAX. DF AT +25 °C 120 Hz (%)	MAX. ESR AT + 25 °C 100 kHz (m $\Omega$ )	MAX. RIPPLE, 100 kHz I <sub>RMS</sub> (A)
<b>50 V<sub>DC</sub> AT +105 °C, 33 V<sub>DC</sub> AT +125 °C</b>						
45	E2	20021-247(1)(2)	220	10	50	3.464
66	E3	20021-248(1)(2)	330	10	35	4.140
66	3E	20021-249(1)(2)	330	10	35	4.140
95	E2	20021-250(1)(2)	470	10	50	3.464
90	E4	20021-251(1)(2)	440	10	25	4.899
130	E6	20021-252(1)(2)	660	10	17	5.941
130	6E	20021-253(1)(2)	660	10	17	5.941
140	E3	20021-254(1)(2)	705	10	35	4.140
140	3E	20021-255(1)(2)	705	10	35	4.140
190	E4	20021-256(1)(2)	940	10	25	4.899
280	E6	20021-257(1)(2)	1410	10	17	5.941
280	6E	20021-258(1)(2)	1410	10	17	5.941
<b>63 V<sub>DC</sub> AT +105 °C, 43 V<sub>DC</sub> AT +125 °C</b>						
30	E2	20021-259(1)(2)	190	10	50	3.464
45	E2	20021-260(1)(2)	278	10	50	3.464
45	E3	20021-261(1)(2)	285	10	35	4.140
45	3E	20021-262(1)(2)	285	10	35	4.140
60	E4	20021-263(1)(2)	380	10	25	4.899
66	E3	20021-264(1)(2)	417	10	35	4.140
66	3E	20021-265(1)(2)	417	10	35	4.140
90	E4	20021-266(1)(2)	556	10	25	4.899
90	E6	20021-267(1)(2)	570	10	17	5.941
90	6E	20021-268(1)(2)	570	10	17	5.941
130	E6	20021-269(1)(2)	834	10	17	5.941
130	6E	20021-270(1)(2)	834	10	17	5.941
<b>75 V<sub>DC</sub> AT +105 °C, 50 V<sub>DC</sub> AT +125 °C</b>						
45	E2	20021-271(1)(2)	330	12	50	3.464
66	E3	20021-272(1)(2)	495	12	35	4.140
66	3E	20021-273(1)(2)	495	12	35	4.140
90	E4	20021-274(1)(2)	660	12	25	4.899
130	E6	20021-275(1)(2)	990	12	17	5.941
130	6E	20021-276(1)(2)	990	12	17	5.941

**Notes**

- Part number definitions:  
(1) Surge current: blank, A, B, S  
(2) Packaging: blank, /HR

**POWER DISSIPATION**

CASE CODE	MAXIMUM PERMISSIBLE POWER DISSIPATION AT +45 °C (W) WITH 30 °C RISE IN FREE AIR
EE	0.44
E2, E3, E4, E6, 3E, 6E	0.60

**STANDARD PACKAGING QUANTITY**

CASE CODE	QUANTITY (PCS/REEL)	
	7" REEL	½ REEL
EE	400	200

**Note**

- Contact factory for stack capacitors packing and board mounting options





PERFORMANCE CHARACTERISTICS (for Discrete Capacitors T54EE)				
ITEM	CONDITION	POST TEST PERFORMANCE		
Life test at +85 °C	2000 h application of rated voltage at +85 °C, DLA 20021	Capacitance change		Within -20 % / +10 % of initial value
		Dissipation factor		Within initial limits
		Leakage current		Shall not exceed 125 % of initial limit
Life test at +125 °C	2000 h application of 2/3 rated voltage at +125 °C, DLA 20021	Capacitance change		Within -20 % / +10 % of initial value
		Dissipation factor		Within initial limits
		Leakage current		Shall not exceed 125 % of initial limit
Stability at low and high temperatures	DLA 20021	Step 1 (+25 °C)	Capacitance change	Within ± 20 % of initial value
			Dissipation factor	Within initial limit
			Leakage current	Within initial limits
			Equivalent series resistance	Within initial limits
		Step 2 (-55 °C)	Capacitance change	Within -15 % to +10 % from step 1 measured value
			Dissipation factor	Within initial limit
		Step 3 (+25 °C)	Capacitance change	Within -5 % to +5 % from step 1 measured value
			Dissipation factor	Within initial limit
			Leakage current	Within initial limit
		Step 4 (+85 °C)	Capacitance change	Within ± 30 % from step 1 measured value
			Dissipation factor	Shall not exceed 120 % of initial limit
			Leakage current	Shall not exceed 1000 % of initial value
		Step 5 (+125 °C)	Capacitance change	Within ± 40 % from step 1 measured value
			Dissipation factor	Shall not exceed 150 % of initial limit
			Leakage current	Shall not exceed 1000 % of initial limit
		Step 6 (+25 °C)	Capacitance change	Within -10 % to +5 % from step 1 measured value
			Dissipation factor	Within initial limit
			Leakage current	Within initial limit
			Equivalent series resistance	Within initial limit
Surge voltage	+85 °C, 1000 successive test cycles at 1.32 of rated voltage DLA 20021	Capacitance change		Within -20 % to +5 % of initial value
		Dissipation factor		Within initial limit
		Leakage current		Shall not exceed 300 % of initial limit
		Equivalent series resistance		Within initial limit
Resistance to soldering heat	DLA 20021	Capacitance change		Within ± 10 % of initial value
		Dissipation factor		Within initial limit
		Leakage current		Within initial limit
Vibration, high frequency	DLA 20021	Capacitors shall be visually examined for evidence of mechanical damage		

PRODUCT INFORMATION	
Polymer Guide	<a href="http://www.vishay.com/doc?40076">www.vishay.com/doc?40076</a>
Moisture Sensitivity	<a href="http://www.vishay.com/doc?40135">www.vishay.com/doc?40135</a>
Infographic	<a href="http://www.vishay.com/doc?48084">www.vishay.com/doc?48084</a>
Sample Board	<a href="http://www.vishay.com/doc?48073">www.vishay.com/doc?48073</a>
FAQ	
Frequently Asked Questions	<a href="http://www.vishay.com/doc?42106">www.vishay.com/doc?42106</a>



## Guide for Tantalum Solid Electrolyte Chip Capacitors With Polymer Cathode

### INTRODUCTION

Tantalum electrolytic capacitors are the preferred choice in applications where volumetric efficiency, stable electrical parameters, high reliability, and long service life are primary considerations. The stability and resistance to elevated temperatures of the tantalum/tantalum oxide/manganese dioxide system make solid tantalum capacitors an appropriate choice for today's surface mount assembly technology.

Vishay Sprague has been a pioneer and leader in this field, producing a large variety of tantalum capacitor types for consumer, industrial, automotive, military, and aerospace electronic applications.

Tantalum is not found in its pure state. Rather, it is commonly found in a number of oxide minerals, often in combination with Columbium ore. This combination is known as "tantalite" when its contents are more than one-half tantalum. Important sources of tantalite include Australia, Brazil, Canada, China, and several African countries. Synthetic tantalite concentrates produced from tin slags in Thailand, Malaysia, and Brazil are also a significant raw material for tantalum production.

Electronic applications, and particularly capacitors, consume the largest share of world tantalum production. Other important applications for tantalum include cutting tools (tantalum carbide), high temperature super alloys, chemical processing equipment, medical implants, and military ordnance.

Vishay Sprague is a major user of tantalum materials in the form of powder and wire for capacitor elements and rod and sheet for high temperature vacuum processing.

### THE BASICS OF TANTALUM CAPACITORS

Most metals form crystalline oxides which are non-protecting, such as rust on iron or black oxide on copper. A few metals form dense, stable, tightly adhering, electrically insulating oxides. These are the so-called "valve" metals and include titanium, zirconium, niobium, tantalum, hafnium, and aluminum. Only a few of these permit the accurate control of oxide thickness by electrochemical means. Of these, the most valuable for the electronics industry are aluminum and tantalum.

Capacitors are basic to all kinds of electrical equipment, from radios and television sets to missile controls and automobile ignitions. Their function is to store an electrical charge for later use.

Capacitors consist of two conducting surfaces, usually metal plates, whose function is to conduct electricity. They are separated by an insulating material or dielectric. The dielectric used in all tantalum electrolytic capacitors is tantalum pentoxide.

Tantalum pentoxide compound possesses high-dielectric strength and a high-dielectric constant. As capacitors are being manufactured, a film of tantalum pentoxide is applied to their electrodes by means of an electrolytic process. The film is applied in various thicknesses and at various voltages and although transparent to begin with, it takes on different colors as light refracts through it. This coloring occurs on the tantalum electrodes of all types of tantalum capacitors.

Rating for rating, tantalum capacitors tend to have as much as three times better capacitance/volume efficiency than aluminum electrolytic capacitors. An approximation of the capacitance/volume efficiency of other types of capacitors may be inferred from the following table, which shows the dielectric constant ranges of the various materials used in each type. Note that tantalum pentoxide has a dielectric constant of 26, some three times greater than that of aluminum oxide. This, in addition to the fact that extremely thin films can be deposited during the electrolytic process mentioned earlier, makes the tantalum capacitor extremely efficient with respect to the number of microfarads available per unit volume. The capacitance of any capacitor is determined by the surface area of the two conducting plates, the distance between the plates, and the dielectric constant of the insulating material between the plates.

### COMPARISON OF CAPACITOR DIELECTRIC CONSTANTS

DIELECTRIC	$\epsilon$ DIELECTRIC CONSTANT
Air or vacuum	1.0
Paper	2.0 to 6.0
Plastic	2.1 to 6.0
Mineral oil	2.2 to 2.3
Silicone oil	2.7 to 2.8
Quartz	3.8 to 4.4
Glass	4.8 to 8.0
Porcelain	5.1 to 5.9
Mica	5.4 to 8.7
Aluminum oxide	8.4
<b>Tantalum pentoxide</b>	<b>26</b>
Ceramic	12 to 400K

In the tantalum electrolytic capacitor, the distance between the plates is very small since it is only the thickness of the tantalum pentoxide film. As the dielectric constant of the tantalum pentoxide is high, the capacitance of a tantalum capacitor is high if the area of the plates is large:

$$C = \frac{\epsilon A}{t}$$

where

C = capacitance

$\epsilon$  = dielectric constant

A = surface area of the dielectric

t = thickness of the dielectric

Tantalum capacitors contain either liquid or solid electrolytes. In solid electrolyte capacitors, a dry material (manganese dioxide) forms the cathode plate. A tantalum lead is embedded in or welded to the pellet, which is in turn connected to a termination or lead wire. The drawings show the construction details of the surface mount types of tantalum capacitors shown in this catalog.

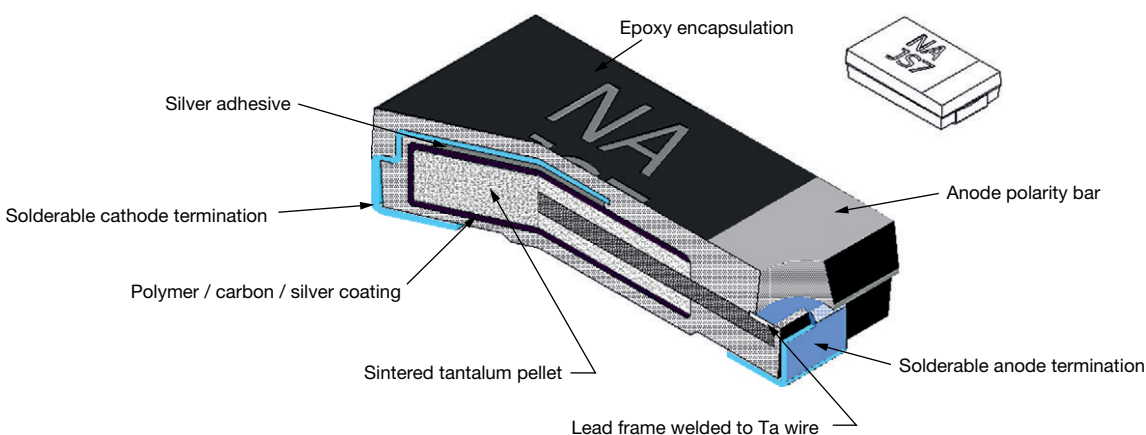
## SOLID ELECTROLYTE POLYMER TANTALUM CAPACITORS

Solid electrolyte polymer capacitors utilize sintered tantalum pellets as anodes. Tantalum pentoxide dielectric layer is formed on the entire surface of anode, which is further impregnated with highly conductive polymer as cathode system.

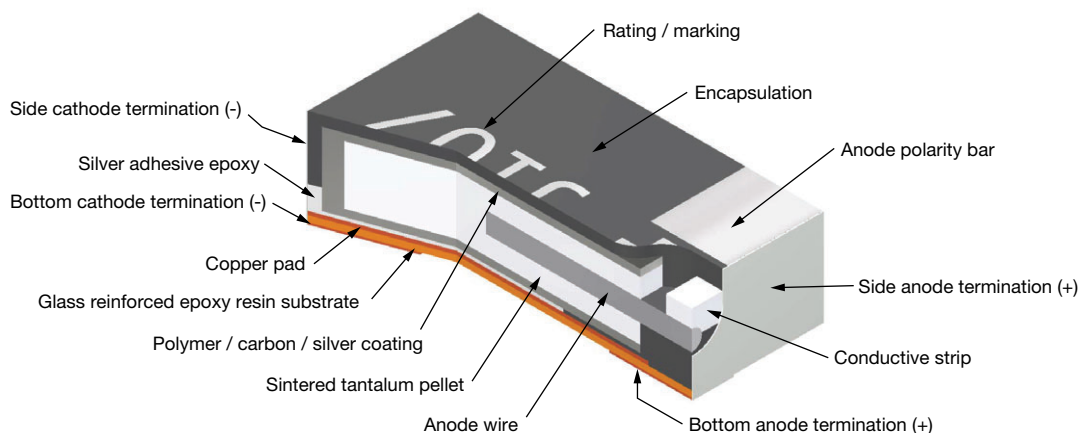
The conductive polymer layer is then coated with graphite, followed by a layer of metallic silver, which provides a conductive surface between the capacitor element and the outer termination (lead frame or other).

Molded chip polymer tantalum capacitor encases the element in plastic resins, such as epoxy materials. The molding compound has been selected to meet the requirements of UL 94 V-0 and outgassing requirements of ASTM E-595. After assembly, the capacitors are tested and inspected to assure long life and reliability. It offers excellent reliability and high stability for variety of applications in electronic devices. Usage of conductive polymer cathode system provides very low equivalent series resistance (ESR), which makes the capacitors particularly suitable for high frequency applications.

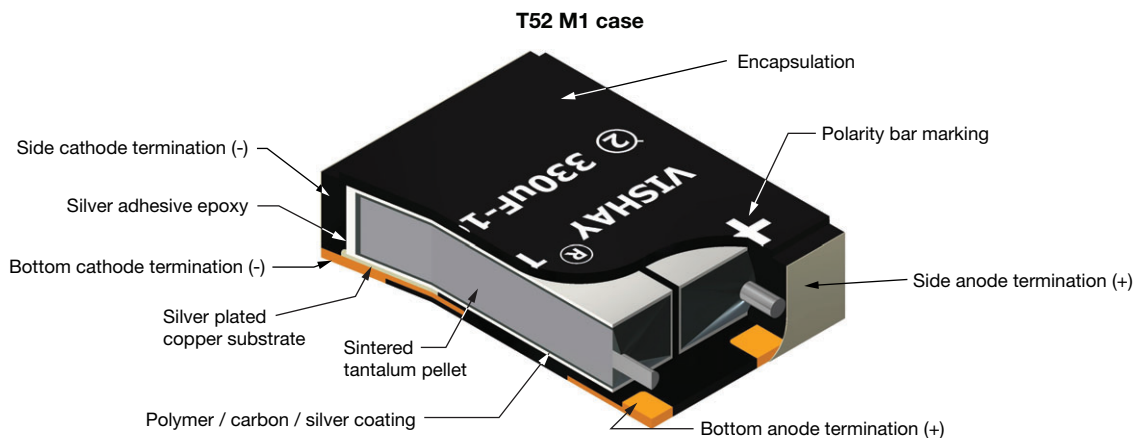
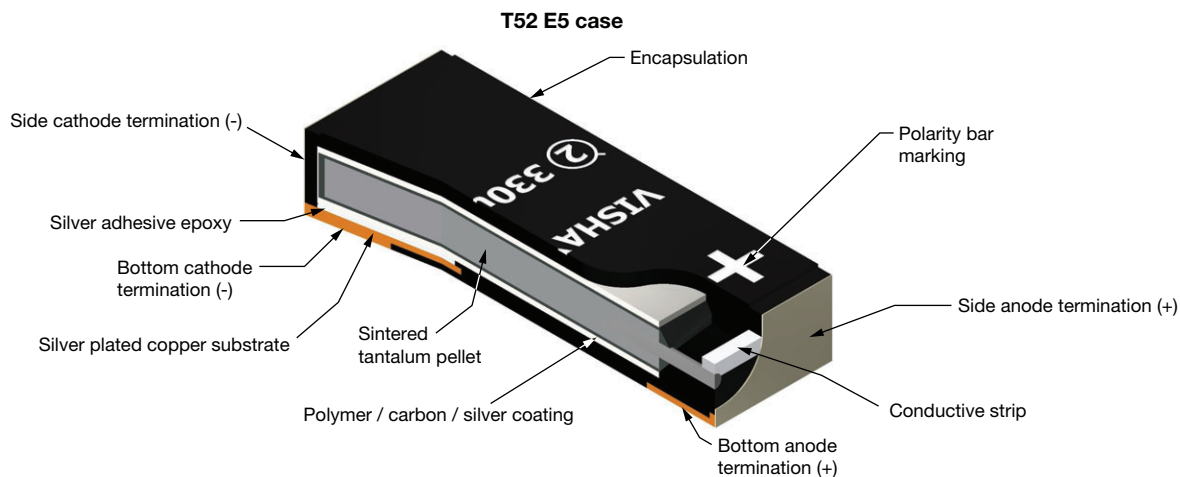
### TANTALUM CAPACITOR WITH POLYMER CATHODE TYPE T50 / T51 / T55 / T56 / 04051



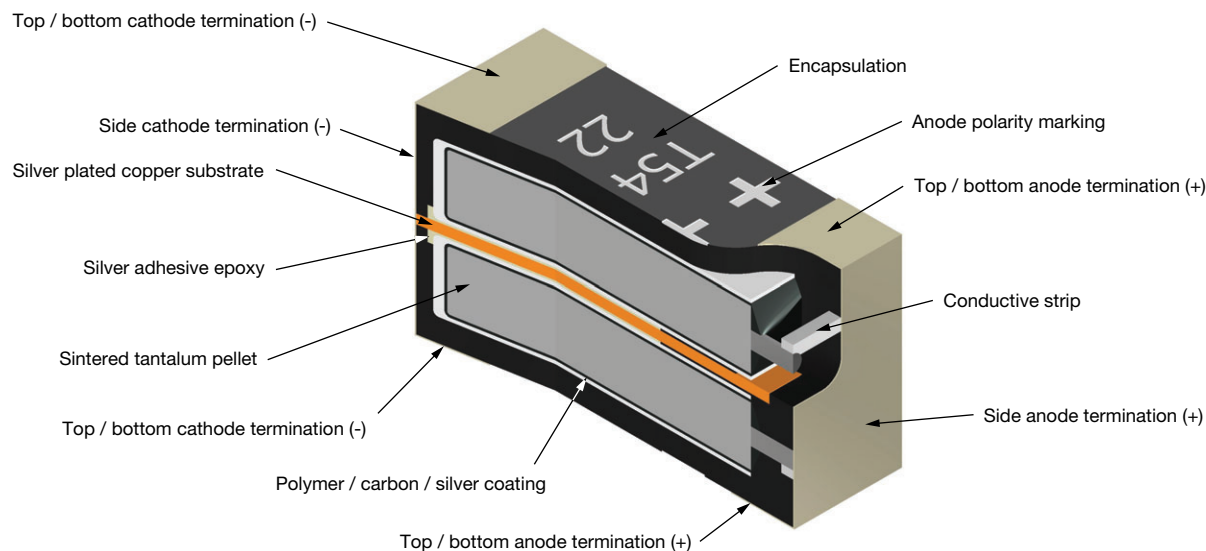
### TANTALUM CAPACITOR WITH POLYMER CATHODE TYPE T58



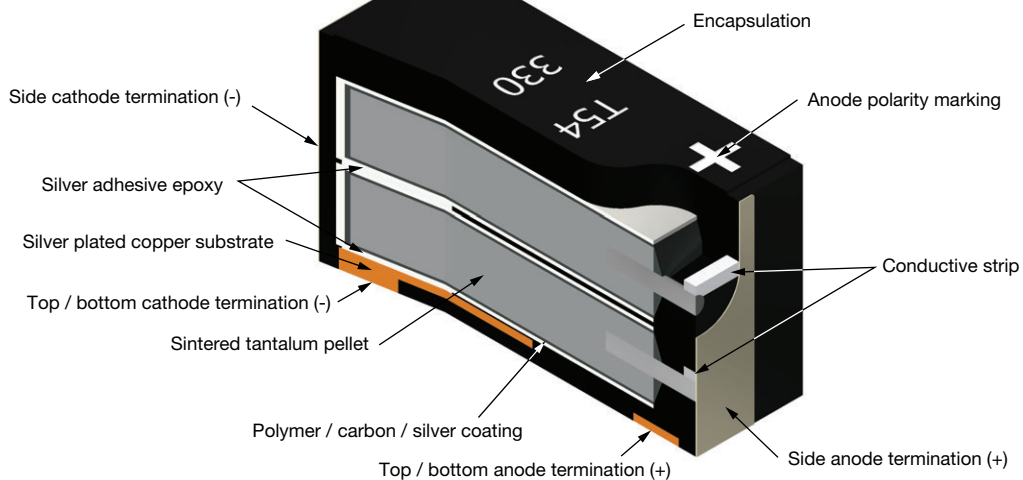
## TANTALUM CAPACITOR WITH POLYMER CATHODE TYPE T52



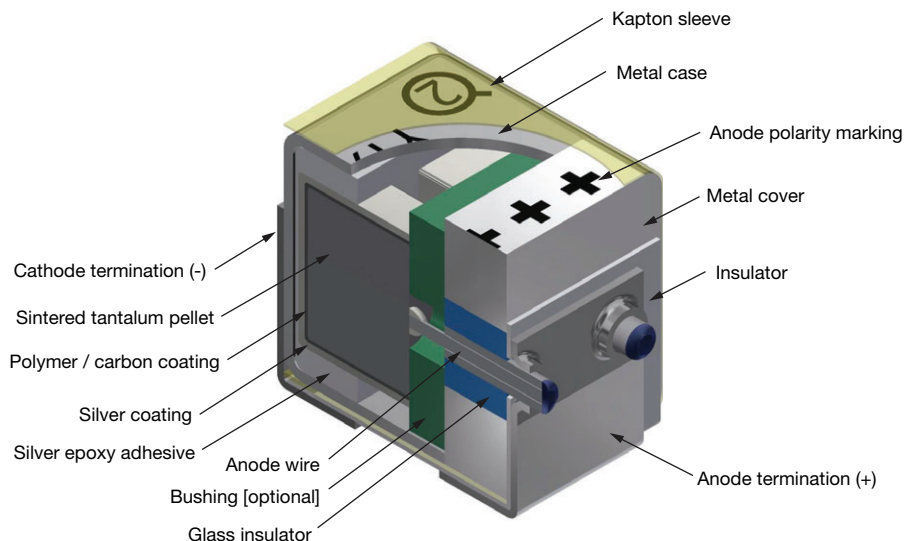
## TANTALUM CAPACITOR WITH POLYMER CATHODE TYPE T54 / T59 / 20021




### T54 EL case



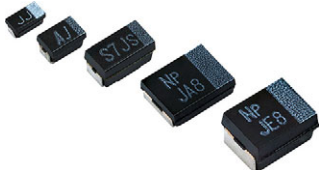
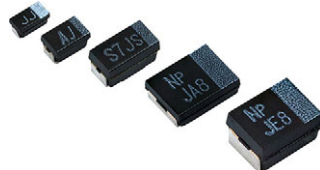
## HERMETICALLY SEALED TANTALUM CAPACITOR WITH POLYMER CATHODE TYPE T27


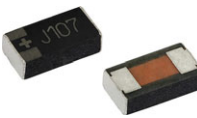

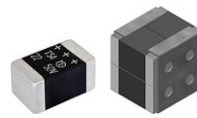



## POLYMER CAPACITORS - METAL CASE, HERMETICALLY SEALED

SERIES	T27
PRODUCT IMAGE	
TYPE	VPolyTan™ hermetically sealed polymer surface-mount chip capacitors, low ESR
FEATURES	Hermetically sealed in metal case, low ESR / low DCL, hi-rel. processing
TEMPERATURE RANGE	-55 °C to +125 °C
CAPACITANCE RANGE	15 µF to 470 µF
VOLTAGE RANGE	16 V to 75 V
CAPACITANCE TOLERANCE	± 20 %
LEAKAGE CURRENT	0.05 CV
DISSIPATION FACTOR	12 %
ESR	25 mΩ to 100 mΩ
CASE SIZES	D
TERMINATION FINISH	100 % tin; tin / lead

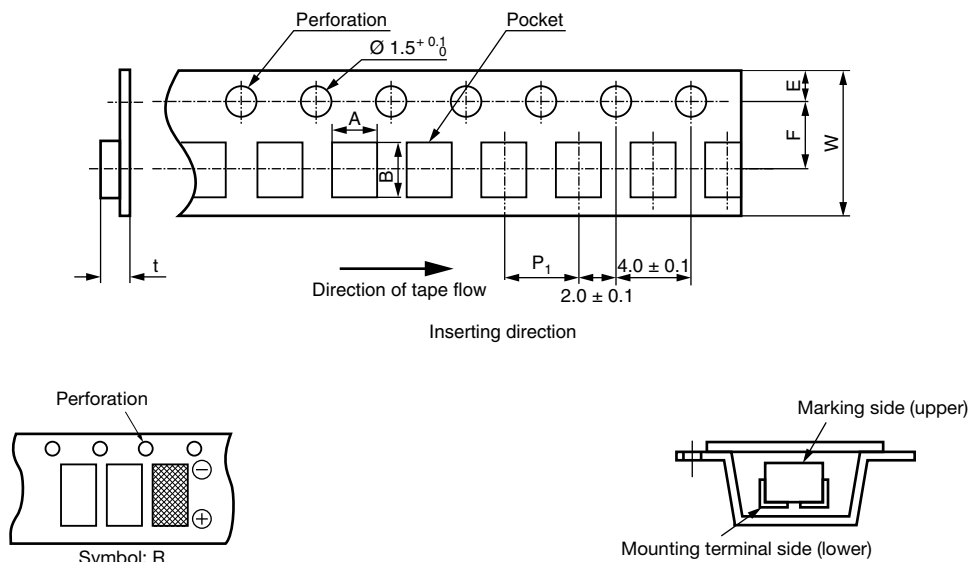


POLYMER CAPACITORS - MOLDED CASE		
SERIES	T50, T51, T55, T56	04051
PRODUCT IMAGE		
TYPE	VPolyTan™, molded case, high performance polymer	VPolyTan™, molded case, high performance polymer
FEATURES	High performance	High performance
TEMPERATURE RANGE	-55 °C to +105 °C / +125 °C	-55 °C to +125 °C (above +105 °C, voltage derating is required)
CAPACITANCE RANGE	3.3 µF to 1000 µF	4.7 µF to 680 µF
VOLTAGE RANGE	2.5 V to 63 V	2.5 V to 63 V
CAPACITANCE TOLERANCE	± 20 %	± 10 %, ± 20 %
LEAKAGE CURRENT	0.1 CV	0.1 CV
DISSIPATION FACTOR	8 % to 10 %	8 % to 10 %
ESR	6 mΩ to 500 mΩ	25 mΩ to 125 mΩ
CASE SIZES	J, P, A, T, B, Z, V, D, C	B, D
TERMINATION FINISH	Cases J, P, C: 100 % tin Case A, T, B, Z, V, D: Ni / Pd / Au	All cases: tin / lead (SnPb)

POLYMER CAPACITORS - LEADFRAMELESS MOLDED CASE					
SERIES	T52	T58	T59	T54	20021
PRODUCT IMAGE					
TYPE	vPolyTan™ polymer surface mount chip capacitors, low profile, leadframeless molded type	vPolyTan™ polymer surface mount chip capacitors, compact, leadframeless molded type	vPolyTan™ polymer surface mount chip capacitors, low ESR, leadframeless molded type	vPolyTan™ polymer surface mount chip capacitors, low ESR, leadframeless molded type, hi-rel commercial off-the-shelf (COTS)	vPolyTan™ polymer surface mount chip capacitors, low ESR, leadframeless molded type, DLA approved
FEATURES	Low profile	Small case size	Multianode	Hi-rel COTS, multianode	Multianode
TEMPERATURE RANGE	-55 °C to +105 °C	-55 °C to +105 °C	-55 °C to +125 °C	-55 °C to +125 °C	-55 °C to +125 °C
CAPACITANCE RANGE	47 µF to 470 µF	1 µF to 100 µF	15 µF to 470 µF	15 µF to 470 µF (discrete capacitors) 30 µF to 2800 µF (stacked capacitors)	15 µF to 470 µF (discrete capacitors) 30 µF to 2800 µF (stacked capacitors)
VOLTAGE RANGE	10 V to 35 V	6.3 V to 35 V	16 V to 75 V	16 V to 75 V	16 V to 75 V
CAPACITANCE TOLERANCE	± 20 %	± 20 %	± 10 %, ± 20 %	± 20 %	± 20 %
LEAKAGE CURRENT	0.1 CV				
DISSIPATION FACTOR	10 %	8 % to 14 %	10 % to 12 %	10 % to 12 %	10 % to 12 %
ESR	40 mΩ to 200 mΩ	90 mΩ to 500 mΩ	20 mΩ to 150 mΩ	5 mΩ to 150 mΩ	5 mΩ to 150 mΩ
CASE SIZES	E5, M1, M9, B2	MM, W0, W9, A0, BB	EE, EL	EE, EL, E2, E3, E4, E6, 3E, 6E	EE, E2, E3, E4, E6, 3E, 6E
TERMINATION	100 % tin		100 % tin; tin / lead		Tin / lead

## MOLDED CAPACITORS, T50 / T51 / T55 / T56 / 04051 TYPES

### PLASTIC TAPE SIZE DIMENSIONS in millimeters



CASE CODE	$A \pm 0.2$	$B \pm 0.2$	$W \pm 0.3$	$F \pm 0.1$	$E \pm 0.1$	$P_1 \pm 0.1$	$t_{\text{max.}}$
J	1.0	1.8	8.0	3.5	1.75	4.0	1.3
P	1.4	2.2	8.0	3.5	1.75	4.0	1.6
A	1.9	3.5	8.0	3.5	1.75	4.0	2.5
T	3.1	3.8	8.0	3.5	1.75	4.0	1.7
B	3.1	3.8	8.0	3.5	1.75	4.0	2.5
C	3.7	6.3	12.0	5.5	1.75	8.0	3.1
Z	4.8	7.7	12.0	5.5	1.75	8.0	2.6
V	4.8	7.7	12.0	5.5	1.75	8.0	2.6
D	4.8	7.7	12.0	5.5	1.75	8.0	3.4

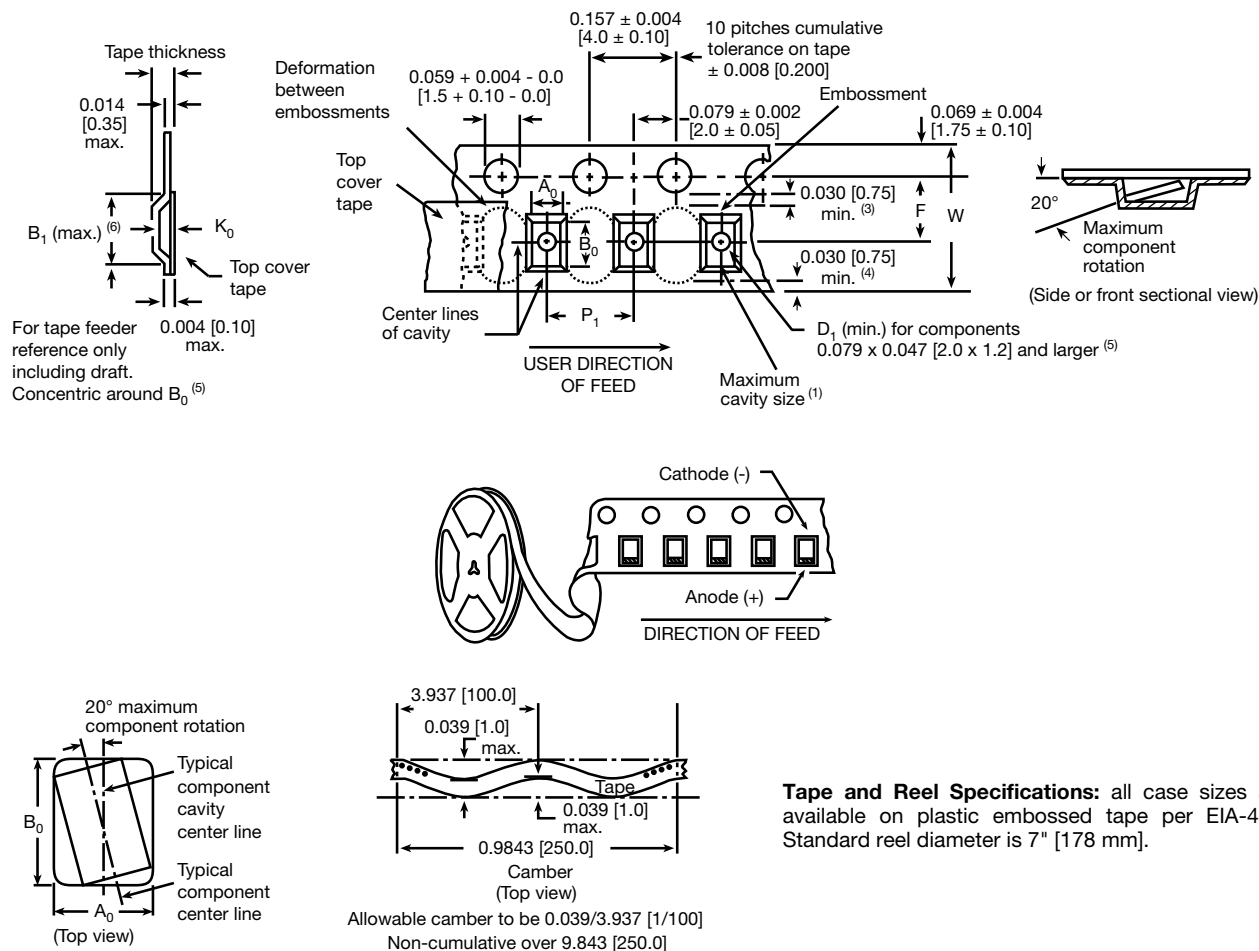
#### Note

- A reel diameter of 330 mm is also applicable



## LEADFRAMELESS MOLDED CAPACITORS, ALL TYPES

### PLASTIC TAPE AND REEL PACKAGING in inches [millimeters]



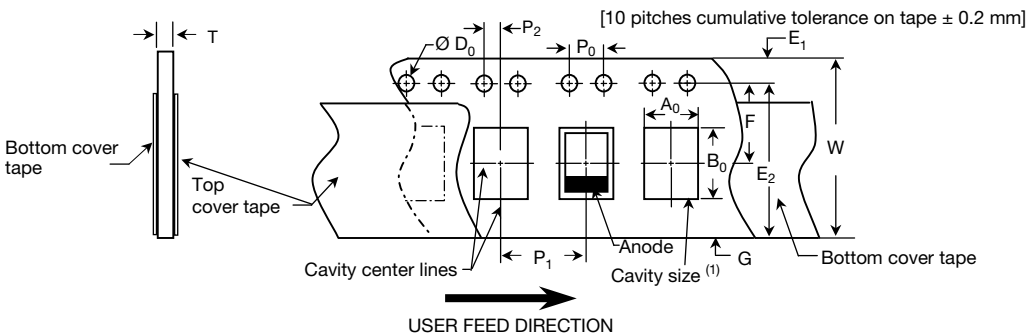
#### Notes

- Metric dimensions will govern. Dimensions in inches are rounded and for reference only
- $A_0$ ,  $B_0$ ,  $K_0$ , are determined by the maximum dimensions to the ends of the terminals extending from the component body and / or the body dimensions of the component. The clearance between the ends of the terminals or body of the component to the sides and depth of the cavity ( $A_0$ ,  $B_0$ ,  $K_0$ ) must be within 0.002" (0.05 mm) minimum and 0.020" (0.50 mm) maximum. The clearance allowed must also prevent rotation of the component within the cavity of not more than 20°
- Tape with components shall pass around radius "R" without damage. The minimum trailer length may require additional length to provide "R" minimum for 12 mm embossed tape for reels with hub diameters approaching N minimum
- This dimension is the flat area from the edge of the sprocket hole to either outward deformation of the carrier tape between the embossed cavities or to the edge of the cavity whichever is less
- This dimension is the flat area from the edge of the carrier tape opposite the sprocket holes to either the outward deformation of the carrier tape between the embossed cavity or to the edge of the cavity whichever is less
- The embossed hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location shall be applied independent of each other
- $B_1$  dimension is a reference dimension tape feeder clearance only

CARRIER TAPE DIMENSIONS in inches [millimeters]								
CASE CODE	TAPE SIZE	B <sub>1</sub> (MAX.) <sup>(1)</sup>	D <sub>1</sub> (MIN.)	F	K <sub>0</sub> (MAX.)	P <sub>1</sub>	P <sub>2</sub>	W
E5	12 mm	0.329 [8.35]	0.059 [1.5]	0.217 ± 0.002 [5.50 ± 0.05]	0.071 [1.8]	0.315 ± 0.004 [8.0 ± 0.10]	0.079 ± 0.002 [2.00 ± 0.05]	0.476 ± 0.008 [12.1 ± 0.20]
MM <sup>(2)</sup>	8 mm	0.075 [1.91]	0.02 [0.5]	0.138 [3.5]	0.043 [1.10]	0.157 [4.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.315 [8.0]
M1, M9	12 mm	0.32 [8.2]	0.059 [1.5]	0.217 ± 0.002 [5.5 ± 0.05]	0.094 [2.39]	0.315 ± 0.04 [8.0 ± 1.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.472 + 0.012 / - 0.004 [12.0 + 0.3 / - 0.10]
W9	8 mm	0.126 [3.20]	0.030 [0.75]	0.138 [3.5]	0.045 [1.15]	0.157 [4.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.315 [8.0]
W0	8 mm	0.126 [3.20]	0.030 [0.75]	0.138 [3.5]	0.045 [1.15]	0.157 [4.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.315 [8.0]
A0	8 mm	-	0.02 [0.5]	0.138 [3.5]	0.049 [1.25]	0.157 [4.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.315 [8.0]
BB	8 mm	0.157 [4.0]	0.039 [1.0]	0.138 [3.5]	0.087 [2.22]	0.157 [4.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.315 [8.0]
EE, EL	12 mm	0.32 [8.2]	0.059 [1.5]	0.217 ± 0.002 [5.5 ± 0.05]	0.175 [4.44]	0.315 ± 0.04 [8.0 ± 1.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.472 + 0.012 / - 0.004 [12.0 + 0.3 / - 0.10]
B2	8 mm	0.157 [4.0]	0.039 [1.0]	0.138 [3.5]	0.057 [1.45]	0.157 [4.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.315 [8.0]
D <sup>(3)</sup>	16 mm	0.321 [8.16]	0.059 [1.5]	0.295 ± 0.004 [7.50 ± 0.1]	0.308 [7.83]	0.472 ± 0.004 [12.00 ± 0.1]	0.079 ± 0.004 [2.00 ± 0.1]	0.630 ± 0.012 [16.00 ± 0.3]

## Notes

- (1) For reference only
- (2) Standard packaging of MM case is with paper tape. Plastic tape is available per request
- (3) Tape thickness 0.018 [0.45] max.

PAPER TAPE AND REEL PACKAGING DIMENSIONS in inches [millimeters]											
											
CASE SIZE	TAPE SIZE	A <sub>0</sub>	B <sub>0</sub>	D <sub>0</sub>	P <sub>0</sub>	P <sub>1</sub>	P <sub>2</sub>	E	F	W	T
MM	8 mm	0.041 ± 0.002 [1.05 ± 0.05]	0.071 ± 0.002 [1.8 ± 0.05]	0.06 ± 0.004 [1.5 ± 0.1]	0.157 ± 0.004 [4.0 ± 0.1]	0.157 ± 0.004 [4.0 ± 0.1]	0.079 ± 0.002 [2.0 ± 0.05]	0.069 ± 0.004 [1.75 ± 0.1]	0.0138 ± 0.002 [3.5 ± 0.05]	0.315 ± 0.008 [8.0 ± 0.2]	0.037 ± 0.002 [0.95 ± 0.05]
M0	8 mm	0.049 ± 0.002 [1.25 ± 0.05]	0.081 ± 0.002 [2.05 ± 0.05]	0.06 ± 0.004 [1.5 ± 0.1]	0.157 ± 0.004 [4.0 ± 0.1]	0.157 ± 0.004 [4.0 ± 0.1]	0.079 ± 0.002 [2.0 ± 0.05]	0.069 ± 0.004 [1.75 ± 0.1]	0.0138 ± 0.002 [3.5 ± 0.05]	0.315 ± 0.008 [8.0 ± 0.2]	0.041 ± 0.002 [1.05 ± 0.05]

## Note

- (1) A<sub>0</sub>, B<sub>0</sub> are determined by the maximum dimensions to the ends of the terminals extending from the component body and / or the body dimensions of the component. The clearance between the ends of the terminals or body of the component to the sides and depth of the cavity (A<sub>0</sub>, B<sub>0</sub>) must be within 0.002" (0.05 mm) minimum and 0.020" (0.50 mm) maximum. The clearance allowed must also prevent rotation of the component within the cavity of not more than 20°

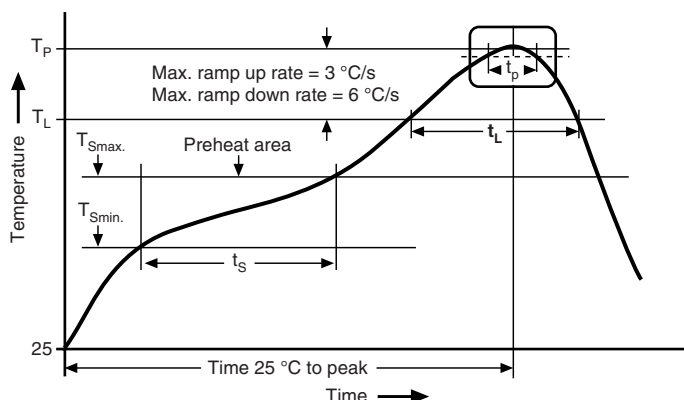
## PACKING AND STORAGE

Polymer capacitors meet moisture sensitivity level rating (MSL) of 3 or 4 as specified in IPC/JEDEC® J-STD-020 and are dry packaged in moisture barrier bags (MBB) per J-STD-033. MSL for each particular family is defined in the datasheet - either in “Features” section or “Standard Ratings” table. Level 3 specifies a floor life (out of bag) of 168 hours and level 4 specifies a floor life of 72 hours at 30 °C maximum and 60 % relative humidity (RH). Unused capacitors should be re-sealed in the MBB with fresh desiccant. A moisture strip (humidity indicator card) is included in the bag to assure dryness. To remove excess moisture, capacitors can be dried at 40 °C (standard “dry box” conditions).

For detailed recommendations please refer to J-STD-033.

## RECOMMENDED REFLOW PROFILES

Vishay recommends no more than 3 cycles of reflow in accordance with J-STD-020.



PROFILE FEATURE	SnPb EUTECTIC ASSEMBLY	LEAD (Pb)-FREE ASSEMBLY
<b>PREHEAT AND SOAK</b>		
Temperature min. ( $T_{Smin.}$ )	100 °C	150 °C
Temperature max. ( $T_{Smax.}$ )	150 °C	200 °C
Time ( $t_s$ ) from ( $T_{Smin.}$ to $T_{Smax.}$ )	60 s to 120 s	60 s to 120 s
<b>RAMP UP</b>		
Ramp-up rate ( $T_L$ to $T_P$ )	3 °C/s maximum	
Liquidus temperature ( $T_L$ )	183 °C	217 °C
Time ( $t_L$ ) maintained above $T_L$	60 s to 150 s	
Peak package body temperature ( $T_P$ ) max.	Depends on type and case - see table below	
Time ( $t_p$ ) within 5 °C of the peak max. temperature	20 s	5 s <sup>(1)</sup>
<b>RAMP DOWN</b>		
Ramp-down rate ( $T_P$ to $T_L$ )	6 °C/s maximum	
Time from 25 °C to peak temperature	6 min maximum	8 min maximum

### Note

<sup>(1)</sup> For T27, lead (Pb)-free capacitors  $t_p = 30$  s

## PEAK PACKAGE BODY TEMPERATURE (T<sub>p</sub>) MAXIMUM

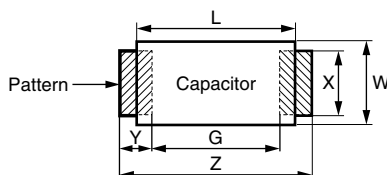
TYPE	CASE CODE	PEAK PACKAGE BODY TEMPERATURE (T <sub>p</sub> ) MAX.	
		SnPb EUTECTIC ASSEMBLY	LEAD (Pb)-FREE ASSEMBLY
T27	D	220 °C	245 °C
T55	J, P, A, T, B, C, Z, V, D	n/a	260 °C
T52	E5, M1, M9, B2		260 °C
T58	MM, W9, W0, A0, BB		260 °C
T50	D		260 °C
T51	D, V		260 °C
T56	B, V		260 °C
T56	D		250 °C
T59	EE, EL	220 °C	250 °C
T54	EL, 3E, 6E, EE, E2, E3, E4, E6	220 °C	250 °C
20021	3E, 6E, EE, E2, E3, E4, E6	220 °C	n/a
04051	D	220 °C	n/a
04051	B	235 °C	n/a
M327001	D	220 °C	n/a
M327001	B, C	235 °C	n/a

### Notes

- T50, T51, T52, T55, T56 (B, V cases), and T58 capacitors are process sensitive.  
PSL classification to JEDEC J-STD-075: R4G
- T54, T59, and T56 (D case) capacitors with 100 % tin termination are process sensitive.  
PSL classification to JEDEC J-STD-075: R6G

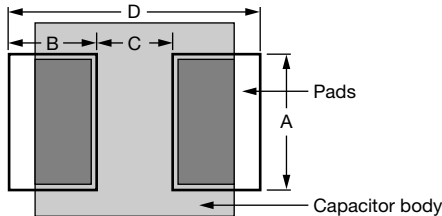
## MOLDED CAPACITORS, T50 / T51 / T55 / T56 / 04051 TYPES

### PAD DIMENSIONS in millimeters

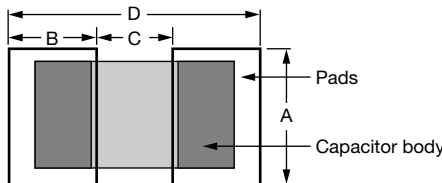


CASE / DIMENSIONS	CAPACITOR SIZE		PAD DIMENSIONS			
	L	W	G (max.)	Z (min.)	X (min.)	Y (Ref.)
J	1.6	0.8	0.7	2.5	1.0	0.9
P	2.0	1.25	0.5	2.6	1.2	1.05
A	3.2	1.6	1.1	3.8	1.5	1.35
T / B	3.5	2.8	1.4	4.1	2.7	1.35
C	5.8	3.2	2.9	6.9	2.7	2.0
Z / V / D	7.3	4.3	4.1	8.2	2.9	2.05

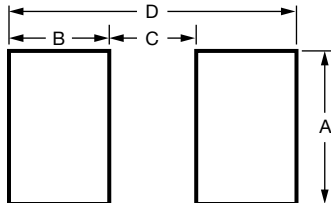
## LEADFRAMELESS MOLDED CAPACITORS T52 / T58

PAD DIMENSIONS in inches [millimeters]					
					
FAMILY	CASE CODE	A (NOM.)	B (MIN.)	C (NOM.)	D (MIN.)
T52	E5	0.094 [2.40]	0.077 [1.95]	0.180 [4.57]	0.333 [8.46]
	M1, M9	0.178 [4.52]	0.098 [2.48]	0.138 [3.50]	0.333 [8.46]
	B2	0.081 [2.06]	0.057 [1.44]	0.070 [1.77]	0.183 [4.64]
T58	MM	0.024 [0.61]	0.027 [0.70]	0.025 [0.64]	0.080 [2.03]
	W0, W9	0.035 [0.89]	0.029 [0.74]	0.041 [1.05]	0.099 [2.52]
	A0	0.047 [1.19]	0.042 [1.06]	0.065 [1.65]	0.148 [3.76]
	BB	0.094 [2.39]	0.044 [1.11]	0.072 [1.82]	0.159 [4.03]

## LEADFRAMELESS MOLDED CAPACITORS T59 / T54 / 20021

PAD DIMENSIONS in inches [millimeters]					
					
FAMILY	CASE CODE	A (NOM.)	B (MIN.)	C (NOM.)	D (MIN.)
T59 / T54	EE	0.209 [5.30]	0.098 [2.50]	0.169 [4.30]	0.366 [9.30]
	EL	0.098 [2.50]	0.098 [2.50]	0.169 [4.30]	0.366 [9.30]
T54	E2 / E3	0.128 [3.24]	0.120 [3.04]	0.154 [3.92]	0.394 [10.0]
	E4 / E6	0.301 [7.64]	0.120 [3.04]	0.154 [3.92]	0.394 [10.0]
	3E	0.482 [12.24]	0.120 [3.04]	0.154 [3.92]	0.394 [10.0]
	6E	0.482 [12.24]	0.120 [3.04]	0.154 [3.92]	0.394 [10.0]
20021	EE	0.209 [5.30]	0.098 [2.50]	0.169 [4.30]	0.366 [9.30]

## HERMETICALLY SEALED CAPACITOR T27 TYPE

PAD DIMENSIONS in inches [millimeters]				
				
CASE CODE	A (MIN.)	B (NOM.)	C (NOM.)	D (NOM.)
D	0.295 [7.50]	0.138 [3.50]	0.100 [2.50]	0.374 [9.50]

## GUIDE TO APPLICATION

1. **AC Ripple Current:** the maximum allowable ripple current shall be determined from the formula:

$$I_{RMS} = \sqrt{\frac{P}{R_{ESR}}}$$

where,

P = power dissipation in W at +45 °C as given in the tables in the product datasheets.

R<sub>ESR</sub> = the capacitor equivalent series resistance at the specified frequency.

2. **AC Ripple Voltage:** the maximum allowable ripple voltage shall be determined from the formula:

$$V_{RMS} = Z \sqrt{\frac{P}{R_{ESR}}}$$

or, from the formula:

$$V_{RMS} = I_{RMS} \times Z$$

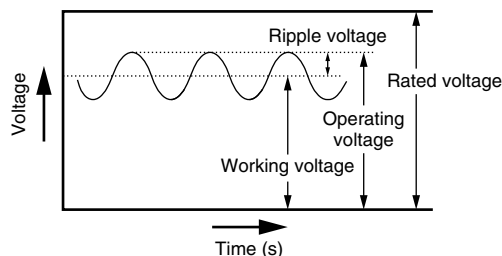
where,

P = power dissipation in W at +45 °C as given in the tables in the product datasheets.

R<sub>ESR</sub> = The capacitor equivalent series resistance at the specified frequency.

Z = The capacitor impedance at the specified frequency.

- 2.1 The tantalum capacitors must be used in such a condition that the sum of the working voltage and ripple voltage peak values does not exceed the rated voltage as shown in figure below.



3. **Temperature Derating:** power dissipation is affected by the heat sinking capability of the mounting surface. If these capacitors are to be operated at temperatures above +45 °C, the permissible ripple current (or voltage) shall be calculated using the derating coefficient as shown in the table below:

MAXIMUM RIPPLE CURRENT TEMPERATURE DERATING FACTOR	
≤ 45 °C	1.0
55 °C	0.8
85 °C	0.6
105 °C	0.4
125 °C	0.25

4. **Reverse Voltage:** the capacitors are not intended for use with reverse voltage applied. However, they are capable of withstanding momentary reverse voltage peaks, which must not exceed the following values:

At 25 °C: 10 % of the rated voltage or 1 V, whichever is smaller.

At 85 °C: 5 % of the rated voltage or 0.5 V, whichever is smaller.

At 105 °C: 3 % of the rated voltage or 0.3 V, whichever is smaller.

5. **Mounting Precautions:**

- 5.1 **Soldering:** capacitors can be attached by conventional soldering techniques; vapor phase, convection reflow, infrared reflow, wave soldering, and hot plate methods. The soldering profile charts show recommended time / temperature conditions for soldering. Preheating is recommended. The recommended maximum ramp rate is 3 °C per second. Attachment with a soldering iron is not recommended due to the difficulty of controlling temperature and time at temperature. The soldering iron must never come in contact with the capacitor. For details see [www.vishay.com/doc?40214](http://www.vishay.com/doc?40214).

- 5.2 **Limit Pressure on Capacitor Installation with Mounter:** pressure must not exceed 4.9 N with a tool end diameter of 1.5 mm when applied to the capacitors using an absorber, centering tweezers, or similar (maximum permitted pressurization time: 5 s). An excessively low absorber setting position would result in not only the application of undue force to the capacitors but capacitor and other component scattering, circuit board wiring breakage, and / or cracking as well, particularly when the capacitors are mounted together with other chips having a height of 1 mm or less.

- 5.3 **Flux Selection**

- 5.3.1 Select a flux that contains a minimum of chlorine and amine.

- 5.3.2 After flux use, the chlorine and amine in the flux remain must be removed.

- 5.4 **Cleaning After Mounting:** the following solvents are usable when cleaning the capacitors after mounting. Never use a highly active solvent.

- Halogen organic solvent (HCFC225, etc.)
- Alcoholic solvent (IPA, ethanol, etc.)
- Petroleum solvent, alkali saponifying agent, water, etc.

Circuit board cleaning must be conducted at a temperature of not higher than 50 °C and for an immersion time of not longer than 30 minutes. When an ultrasonic cleaning method is used, cleaning must be conducted at a frequency of 48 kHz or lower, at an vibrator output of 0.02 W/cm<sup>3</sup>, at a temperature of not higher than 40 °C, and for a time of 5 minutes or shorter.

### Notes

- Care must be exercised in cleaning process so that the mounted capacitor will not come into contact with any cleaned object or the like or will not get rubbed by a stiff brush or similar. If such precautions are not taken particularly when the ultrasonic cleaning method is employed, terminal breakage may occur
- When performing ultrasonic cleaning under conditions other than stated above, conduct adequate advance checkout



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